

<b>Notice of References Cited</b>		Application/Control No. 10/028,610	Applicant(s)/Patent Under Reexamination OMSTEAD ET AL.	
		Examiner Matthew J Song	Art Unit 1765	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,879,459	03-1999	Gadgil et al.	118/715
	B	US-6,143,082	11-2000	McInerney et al.	118/719
	C	US-6,143,128	11-2000	Ameen et al.	156/345.24
	D	US-5,251,148	10-1993	Haines et al.	700/282
	E	US-4,545,136	10-1985	Izu et al.	34/636
	F	US-5,997,588	12-1999	Goodwin et al.	29/25.01
	G	US-5,781,693	07-1998	Ballance et al.	392/416
	H	US-5,125,360	06-1992	Nakayama et al.	118/730
	I	US-5,866,213	02-1999	Foster et al.	427/573
	J	US-5,916,365	06-1999	Sherman, Arthur	117/92
	K	US-5,656,338	08-1997	Gordon, Roy G.	427/576
	L	US-2002/0195056 a1	12-2002	Sandhu et al.	118/719
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Rossnagel et al. "Plasma enhanced atomic layer deposition of Ta and Ti for interconnect diffusion barriers", Jul/Aug 2000, J. Va. Sci. Technol. B 18(4), pp 2016-2020.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.